


Application Number

10/7.86, 807

H.M. Chen et al.

02/25/04

Group Art Unit



[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Ben H

7/25/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

MEG-02-005

U.S. Patent 6,291,268 to Ho, "Low Cost Method of Testing a Cavity-Up BGA Substrate," discloses a method for testing a BGA substrate.

U.S. Patent 6,162,652 to Dass et al., "Process for Sort Testing C4 Bumped Wafers," describes a method of cleaning and testing bumped wafers.

U.S. Patent 6,143,668 to Dass et al., "KLXX Technology with Integrated Passivation Process, Probe Geometry and Probing Process," describes a wafer testing method utilizing cleaning of bond pads prior to testing.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the printed name.

Stephen B. Ackerman,
Reg. No. 37761